1. Package summary

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Min</th>
<th>Typ</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>D</td>
<td>package length</td>
<td>4.3</td>
<td>-</td>
<td>4.4</td>
<td>4.5</td>
<td>mm</td>
</tr>
<tr>
<td>E</td>
<td>package width</td>
<td>2.4</td>
<td>-</td>
<td>2.6</td>
<td>2.8</td>
<td>mm</td>
</tr>
<tr>
<td>A</td>
<td>seated height</td>
<td>2</td>
<td>-</td>
<td>2.15</td>
<td>2.3</td>
<td>mm</td>
</tr>
<tr>
<td>n&lt;sub&gt;2&lt;/sub&gt;</td>
<td>actual quantity of termination</td>
<td>-</td>
<td>-</td>
<td>2</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>

Table 1. Package summary
2. Package outline

Transfer-moulded thermo-setting plastic small rectangular surface mounted package; 2 connectors

![Package outline diagram]

**DIMENSIONS** (mm are the original dimensions)

<table>
<thead>
<tr>
<th>UNIT</th>
<th>A</th>
<th>A₁</th>
<th>b</th>
<th>c</th>
<th>D</th>
<th>E</th>
<th>H</th>
<th>Q</th>
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</thead>
<tbody>
<tr>
<td>mm</td>
<td>2.3</td>
<td>2.0</td>
<td>0.05</td>
<td>1.6</td>
<td>1.4</td>
<td>0.2</td>
<td>4.5</td>
<td>2.8</td>
</tr>
</tbody>
</table>

**Note**
1. The marking band indicates the cathode.

**Fig. 1. Package outline SMA; PMOS (SOD106)**
3. Soldering

Fig. 2. Reflow soldering footprint for SMA; PMOS (SOD106)

Fig. 3. Wave soldering footprint for SMA; PMOS (SOD106)
4. Legal information

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Date of release: 8 February 2016